

**IN THE CLAIMS**

Please amend the claims as follows:

Claims 1-18 (Cancelled)

19. (Currently Amended) A method of making a connector assembly, comprising:

disposing a first conductive layer over a second conductive layer to define a cable, wherein the first conductive layer is insulated from the second conductive layer;

connecting the first conductive layer to a terminal of a connector plug comprising a part of the connector assembly;

connecting the second conductive layer to another terminal of the connector plug; and

connecting a plurality of capacitors between the first and second conductive layers as a part of the connector assembly.

20. (Original) The method of claim 19, wherein connecting the plurality of capacitors comprises:

removing a portion of the insulation material from the first conductive layer according to a predetermined pattern to expose at least a portion of the first conductive layer;

forming openings through the first conductive layer according to another predetermined pattern;

removing a portion of the insulation material covering the second conductive layer according to the other predetermined pattern to expose at least a portion of the second conductive layer through the opening in the first conductive layer and insulation material;

connecting one terminal of each capacitor to the exposed first conductive layer; and connecting another terminal of each capacitor to the exposed second conductive layer.

21. (Original) The method of claim 19, wherein the first conductive layer, the second conductive layer and the layer of insulation material are flexible.

22. (Original) The method of claim 19, further comprising coating the first and second conductive layers with mylar.

23. (Original) The method of claim 19, further comprising selecting a quantity of the plurality of capacitors and a size of each of the plurality of capacitors to provide a predetermined reduction in equivalent series resistance, voltage droop and settling time.

24. (Withdrawn) A method of making a testing system for an integrated circuit, comprising:  
    forming a chassis for holding the integrated circuit; and  
    forming a connector assembly for attaching a power supply to the integrated circuit,  
wherein forming the connector assembly includes:

        disposing a first conductive layer over a second conductive layer to define a cable, wherein the first conductive layer is insulated from the second conductive layer,  
        connecting the first conductive layer to a terminal of a connector plug,  
        connecting the second conductive layer to another terminal of the connector plug, and

        connecting a plurality of capacitors between the first and second conductive layers.

25. (Withdrawn) The method of claim 24, wherein connecting the plurality of capacitors comprises:

        removing a portion of the insulation material from the first conductive layer according to a predetermined pattern to expose at least a portion of the first conductive layer;

        forming openings through the first conductive layer according to another predetermined pattern;

        removing a portion of the insulation material covering the second conductive layer according to the other predetermined pattern to expose at least a portion of the second conductive layer through the opening in the first conductive layer and insulation material;

        connecting one terminal of each capacitor to the exposed first conductive layer; and

connecting another terminal of each capacitor to the exposed second conductive layer.

26. (Withdrawn) The method of claim 24, further comprising:  
forming a floating and self-aligning suspension system; and  
attaching the connector assembly to the floating and self-aligning suspension system.

27. (Withdrawn) The method of claim 24, wherein forming the floating and self-aligning suspension system comprises:

forming an inner frame;  
attaching a biasing arrangement to the inner frame;  
mounting the connector to the inner frame;  
forming an outer frame to mount on the chassis; and  
disposing the inner frame within the outer frame, wherein the biasing arrangement permits the inner frame to move relative to the outer frame to allow the connector to self-align and attach to a mating connector on the integrated circuit.

28. (Withdrawn) The method of claim 24, wherein the first conductive layer, the second conductive layer and the layer of insulation material are flexible.

29. (Withdrawn) The method of claim 24, further comprising selecting a quantity of the plurality of capacitors and a size of each of the plurality of capacitors to provide a predetermined reduction in equivalent series resistance, voltage droop and settling time.